© Copyright 2005, IPC, Bannock	© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.						
IPC Web Site for Information on I       http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information						
Supplier Information										
Company name*	ny name* Company unique ID			Unique ID Authority			Response Date*			
nsemi						2024-04-11				
Contact Name	Title - Contact		Phone - Contact*			Email - Contact*				
roduct-Env-Stewards Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Enviro Compl		Compliance N		NA			Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Item	n Number Mfr Item Name	Imber Mfr Item Name		Version	Manufacturing Site	Weight*	UOM	Unit Type		
RFD14N	N05LSM FET 50V 100.0 m	Ohm DPAK	2024-04-11		СŊЈ	329.241	mg	Each		
Manufacturing Proccess Information					•		·			
Terminal Plating / Grid Array Material	Terminal Base Alloy J	J-STD-020 MSL Rating	Peak Proces	s Body Temperat	ure Max Time at Peak	Temperature Numbe	r of Reflow Cyc	:les		
Matte Tin (Sn) - annealed CU Alloy 1		1	260	С	30	seconds 3				
Comments										
evel 1 - maximum time at peak temperature during so	Idering is 10-30 seconds									
for more information regarding material composition	please refer to page 3									

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	5.16	mg	Supplier	Silicon (Si)	7440-21-3		5.16	mg	
Die Attach Solder	5.026	mg	Supplier	Silver (Ag)	7440-22-4		0.1257	mg	
			А	Lead (Pb)	7439-92-1	7a	4.6491	mg	
			Supplier	Tin (Sn)	7440-31-5		0.2513	mg	
Lead Frame	167.854	mg	Supplier	Tin (Sn)	7440-31-5		0.168	mg	
			В	Nickel (Ni)	7440-02-0		0.168	mg	
			Supplier	Copper (Cu)	7440-50-8		167.518	mg	
Mold Compound-Black	149.268	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		11.195	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.746	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		123.893	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		13.434	mg	
Plating	1.092	mg	Supplier	Tin (Sn)	7440-31-5		1.092	mg	
Wire Bond - Al	0.841	mg	Supplier	Aluminum (Al)	7429-90-5		0.841	mg	